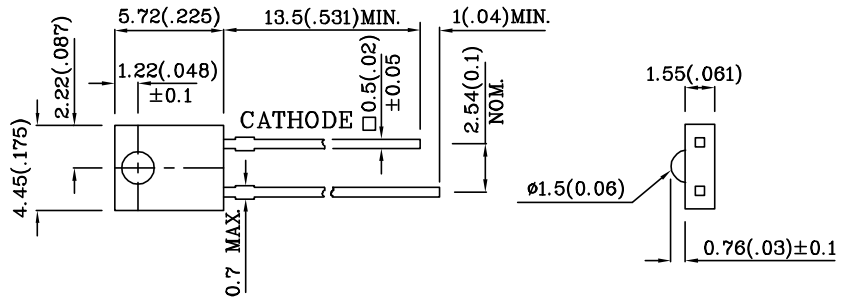


Features

- SIDE LOOKING PACKAGE.
- MECHANICALLY AND SPECTRALLY MATCHED TO THE PHOTOTRANSISTOR.
- WATER CLEAR LENS.
- RoHS COMPLIANT.



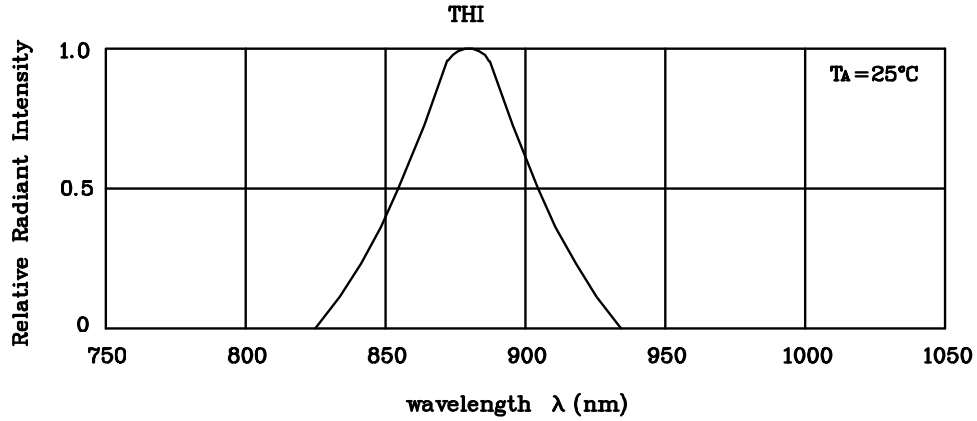
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.

Absolute Maximum Ratings (TA=25°C)		THI (GaAlAs)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	50	mA
Forward Current (Peak) 1/100 Duty Cycle 10us Pulse Width	iFS	1.2	A
Power Dissipation	PT	100	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

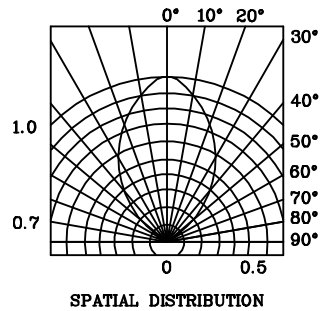
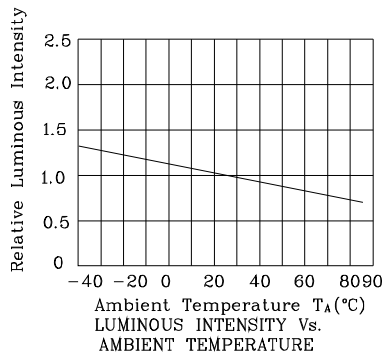
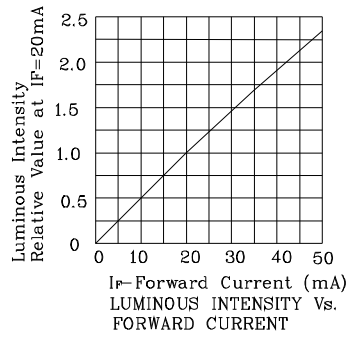
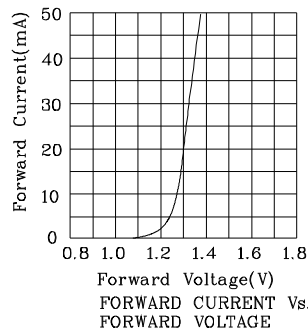
Operating Characteristics (TA=25°C)		THI (GaAlAs)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	1.3	V
Forward Voltage (Max.) (IF=20mA)	VF	1.6	V
Reverse Current (VR=5V)	IR	10	uA
Wavelength of Peak Emission (IF=20mA)	λP	880	nm
Spectral Line Full Width At Half-Maximum (IF=20mA)	$\Delta\lambda$	50	nm
Capacitance (VF=0V, f=1MHz)	C	90	pF

Part Number	Emitting Material	Lens-color	Luminous Intensity Po (Mw/sr) @20mA		Wavelength nm λP	Viewing Angle 2 θ 1/2
			min.	typ.		
XTHI04W	GaAlAs	Water clear	1.0	1.8	880	70°

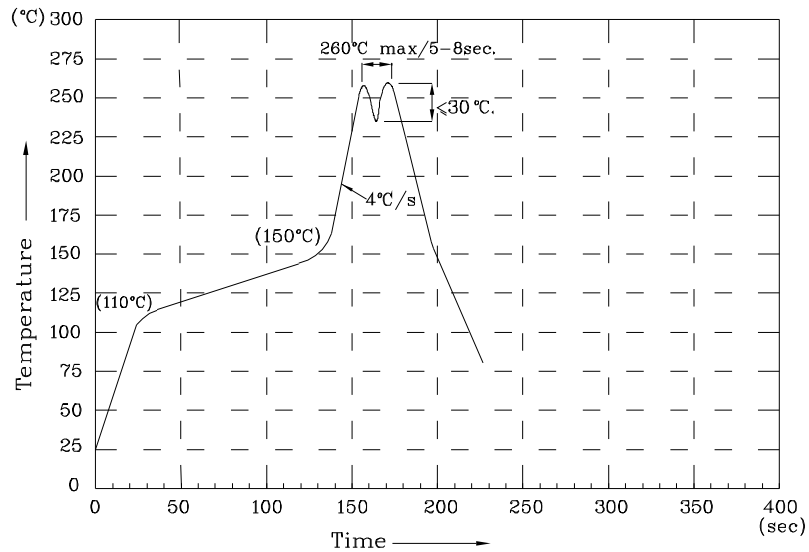


RELATIVE INTENSITY Vs. WAVELENGTH

❖ THI



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage or radiant intensity), the typical accuracy of the sorting process is as follows:

1. Radiant Intensity: +/-15%
2. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.